

SOLDER PASTE

# BGA LEAD SOLDER PASTE



Sn63/Pb37

Melting point 183°C



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# Product Usage



## TIN PASTE

|                      |                                      |
|----------------------|--------------------------------------|
| <b>Model</b>         | BST-506A                             |
| <b>Name</b>          | Moderate temperature<br>Solder paste |
| <b>Composition</b>   | Sn63/Pb37                            |
| <b>Melting point</b> | 183°C                                |
| <b>G.W.</b>          | 50g                                  |
| <b>Granule</b>       | 20~38μm                              |
| <b>Size</b>          | φ50*16mm                             |

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Sn63/Pb37

Lead-containing mid-temperature melting point

183°C





Low residue

Fine grain

Rapid welding

Solder spot bright



# Welding requirements for a wide range of products



**SMT  
patch**



**LED  
patch**



**BGA  
welding**

# Product Size



G.W.:50g

